

NCE N-Channel Super Trench II Power MOSFET

Description

The NCEP11N10AQU uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

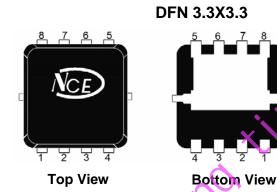
Application

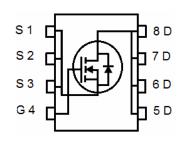
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- V_{DS} =100V,I_D =55A
 - $R_{DS(ON)}$ =10.5m Ω (typical) @ V_{GS} =10V
- $R_{DS(ON)}$ =13.5m Ω (typical) @ V_{GS} =4.5V Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!





Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP11N10AQU	NCEP11N10AQU	DFN3.3X3.3-8L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	55	Α
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	39	Α
Pulsed Drain Current	I _{DM}	220	Α
Maximum Power Dissipation	P _D	70	W
Derating factor		0.56	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	156	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	$R_{ heta JC}$	1.79	°C/W
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NCEP11N10AQU

Electrical Characteristics (T_C=25°C unless otherwise noted)

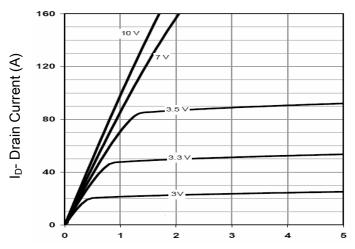
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	100		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	•					
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.1	1.8	2.5	V
Drain-Source On-State Resistance		V _{GS} =10V, I _D =25A	-	10.5	11.8	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =25A	-	13.5	16	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =25A	25	-	-	S
Dynamic Characteristics (Note4)	•		/ 4			
Input Capacitance	C _{lss}	V _{DS} =50V,V _{GS} =0V	-	2050	-	PF
Output Capacitance	Coss		-	180	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	21	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V	-	16	-	nS
Turn-on Rise Time	t _r	V_{DD} =50V, I_D =25A	-	18	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{DD} =50V, I_{D} =25A V_{GS} =10V, R_{G} =3 Ω	-	32	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Qg	V 50V/1 05A	-	42	-	nC
Gate-Source Charge	Q _{gs}	$V_{DS}=50V,I_{D}=25A,$	-	7.8		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	11		nC
Drain-Source Diode Characteristics	10,					
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =25A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	55	Α
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 25A	-	45	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	95	-	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V,L=0.5mH,Rg=25 Ω

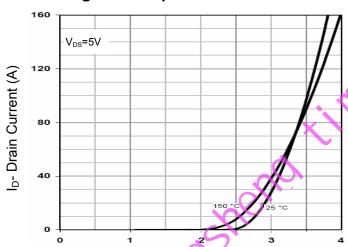


Typical Electrical and Thermal Characteristics



Vds Drain-Source Voltage (V)





Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics

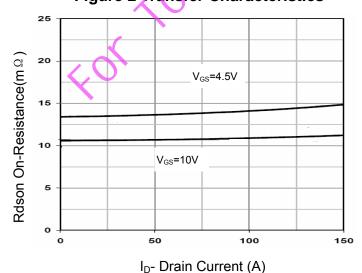


Figure 3 Rdson- Drain Current

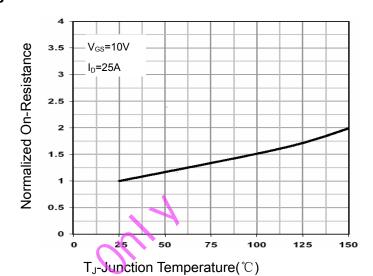


Figure 4 Rdson-Junction Temperature

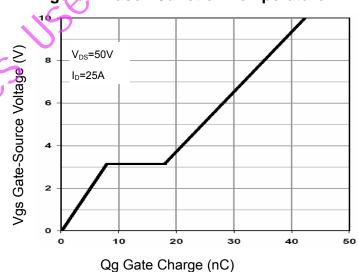
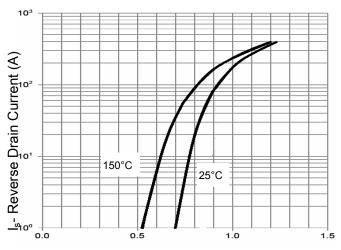


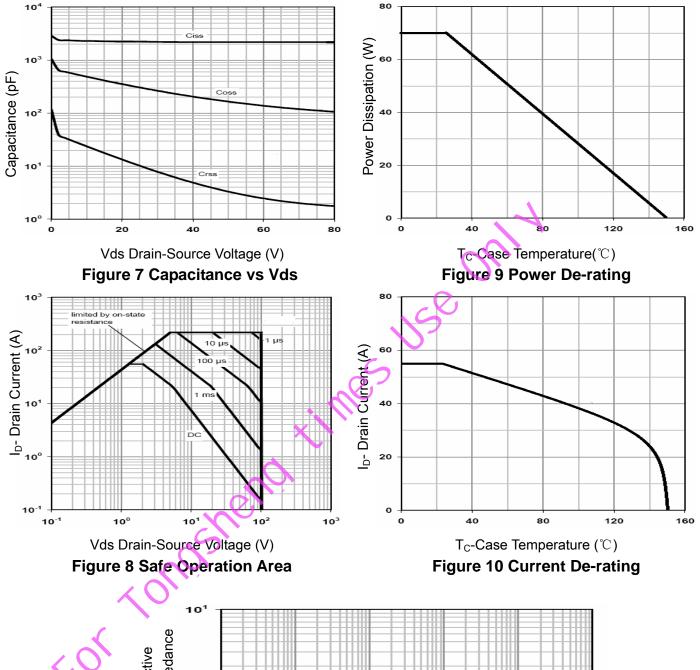
Figure 5 Gate Charge



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward





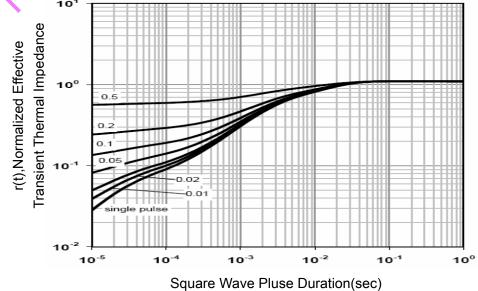
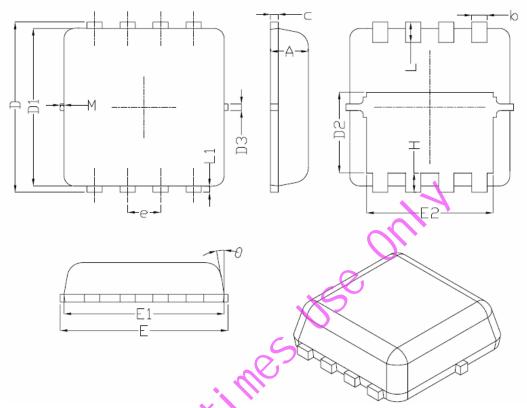


Figure 11 Normalized Maximum Transient Thermal Impedance



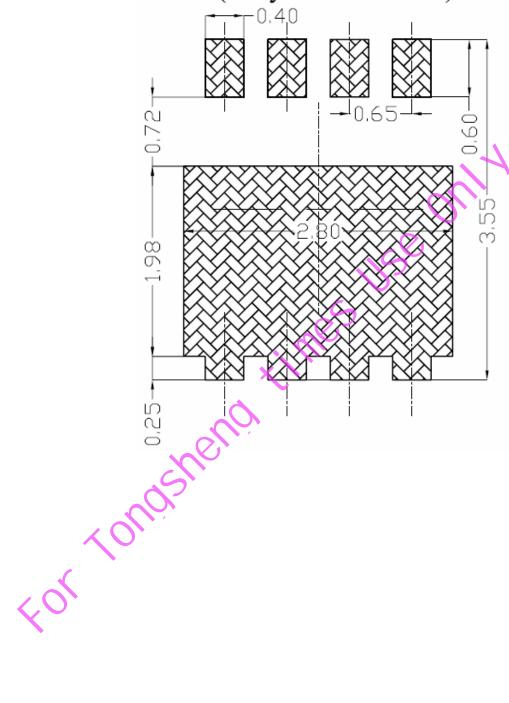
DFN3.3X3.3-8L Package Information



Sumb al	Dimensions In Millimeters				
Symbol	Min.	Nom.	Max.		
A	0.70	0.75	0.80		
b	0.25	0.30	0.35		
С	0.10	0.15	0.25		
D	3.25	3.35	3.45		
D1	3.00	3.10	3.20		
D2	1.48	1.58	1.68		
D3	-	0.13	-		
√ E	3.20	3.30	3.40		
E1	3.00	3.15	3.20		
E2	2.39	2.49	2.59		
е		0.65BSC			
Н	0.30	0.39	0.50		
L	0.30	0.40	0.50		
L1	-	0.13	-		
M	*	*	0.15		
θ		10°	12 [°]		



Land Pattern (Only for Reference)





http://www.ncepower.com

NCEP11N10AQU

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